

ABSTRACT OF THE DISCLOSURE

A device manufacturing method, including: a first process for providing the
5 plural elements on the original substrate via a separation layer in a condition where
terminal sections are exposed to a surface on an opposite side to the separation layer; a
second process for adhering the surface where the terminal sections of the elements to be
transferred on the original substrate are exposed, via conductive adhesive, to a surface of
the final substrate on a side where conductive sections for conducting with the terminal
10 sections of the elements are provided; a third process for producing exfoliation in the
separation layer between the original substrate and the final substrate; and a fourth
process for separating the original substrate from which the transfer of elements has been
completed, from the final substrate.